



MACOM Announces Availability of 226Gbps per Lane Product Family Targeted for 1.6Tbps Optical Modules

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LOWELL, Mass.--(BUSINESS WIRE)--Mar. 7, 2023-- MACOM Technology Solutions Inc. ("MACOM"), a leading supplier of semiconductor products, announced today the release of a 226Gbps per lane technology product family that can enable the development of 1.6TB optical modules.

The product family includes MACOM transimpedance amplifiers ("TIAs") MATA-40734 and MATA-40736, Externally Modulated Laser ("EML") driver MAOM-011112 and photodiode MARP-BP112. The TIAs allow for a data rate of up to 226.8Gbps per lane to support KP4 and IEEE concatenated Forward Error Correction (FEC) with 750um spacing to photodetectors to minimize channel-to-channel cross talk. TIAs for both wire-bonded and flip-chip applications are available. The EML driver is a single-channel flip-chip device enabling ultra-low inductance interfaces for optimum performance and minimum size in an optical module design. Its high bandwidth and high swing can help deliver industry-leading optical performance. The photodiode is also a flip-chip design with high responsivity and an integrated lens for improved alignment tolerance. It is available in both singlet and array form factor.

Bringing this product family to market extends MACOM's portfolio of products to 1.6Tbps small form-factor optical module applications. By increasing the data rate per wavelength from 112Gbps to 226Gbps, MACOM's chipset can cut by half the number of fibers required to carry 1.6Tbits of traffic, with the potential to enable reuse of existing 800Gbps fiber plant for 1.6Tbps applications and development of higher density optical modules.

These products will be displayed at the Optical Fiber Communication Conference and Exhibition (OFC) in San Diego, California, March 7–9, 2023, **Booth #3927**. The 200G per lane technology product family is available for sampling upon request. Email sales@macom.com to learn more.

About MACOM

MACOM designs and manufactures high-performance semiconductor products for the Telecommunications, Industrial and Defense, and Data Center industries. MACOM services over 6,000 customers annually with a broad product portfolio that incorporates RF, Microwave, Analog and Mixed Signal and Optical semiconductor technologies. MACOM has achieved certification to the IATF16949 automotive standard, the AS9100D aerospace standard, the ISO9001 international quality standard and the ISO14001 environmental management standard. MACOM operates facilities across the United States, Europe, Asia and is headquartered in Lowell, Massachusetts. To learn more, visit www.macom.com.

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